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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DESCRIPTION

The LX5518 is a high gain and high power amplifier optimized for 802.11b/g/n applications in the 2.4-2.5 GHz frequency range. The PA is implemented as a three-stage monolithic microwave integrated circuit (MMIC) with active bias, on-chip input matching, and output pre-matching.

The device is manufactured with an InGaP/GaAs Heterojunction Bipolar Transistor (HBT) IC process (MOCVD). It operates with a single positive voltage supply of 3-5V, and provides a power gain of 30dB and an output power of +26dBm at 5V for 3% EVM in the 2.4-2.5GHz.

LX5518 also features an on-chip power detector at the output port of the PA to help reduce BOM cost and PCB space for implementation of power control in a typical wireless system.

The LX5518 is available in a 16-pin 3mm x 3mm quad flat no lead package (QFN 3x3-16L). The compact footprint, low profile, and excellent thermal capability make the LX5518 an ideal solution for 802.11b/g/n applications.

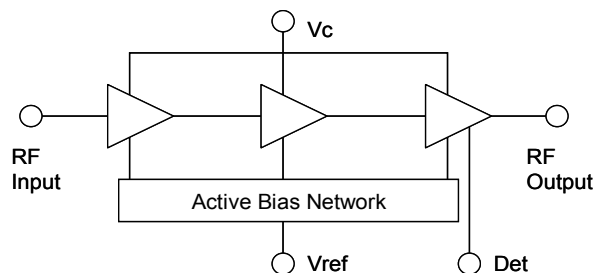
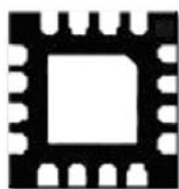
IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

KEY FEATURES

- Advanced InGaP HBT
- 2.4-2.5GHz Operation
- Single-Polarity 3-5V Supply
- Power Gain ~ 30 dB
- 26dBm @3%EVM,802.11g/5V
- 24dBm @3.5%EVM,802.11g/3.3V
- 28dBm @CCK,802.11b/5V
- 27dBm @CCK,802.11b/3.3V
- 24.5% Efficiency @28dBm/5V
- Complete On-Chip Input Match
- Simple Output Match for Optimal EVM
- Temperature-Compensated On-Chip Output Power Detector with Wide Dynamic Range
- Small Footprint: 3x3mm²
- Low Profile: 0.9mm

APPLICATIONS

- 802.11b/g/n

BLOCK DIAGRAM

3X3MM MLP PACKAGE

PACKAGE ORDER INFO
LQ
**Plastic QFN 3x3
16 pin**

RoHS Compliant / Pb-free

LX5518LQ

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX5518LQ-TR)



INFORMATION

Thank you for your interest in Microsemi® Analog Mixed Signal products.

The full data sheet for this device contains proprietary information.

To obtain a copy, please contact your local Microsemi sales representative. The name of your local representative can be obtained at the following link

<http://www.microsemi.com/contact/contactfind.asp>

or

Contact us directly by sending an email to:

IPGdatasheets@microsemi.com

Be sure to specify the data sheet you are requesting and include your company name and contact information and or vcard.

We look forward to hearing from you.